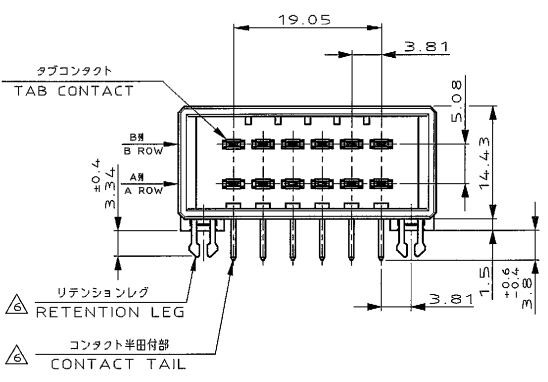
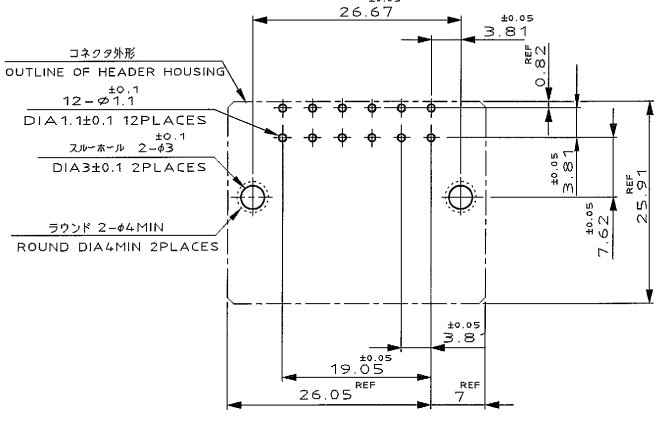
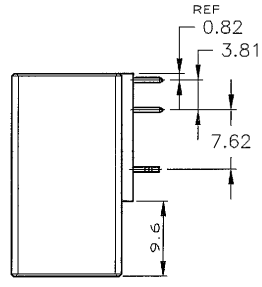
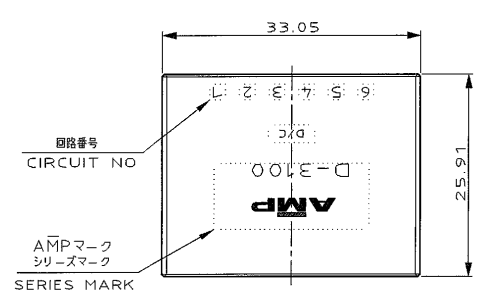


NUMBER 178306
METRIC

PROJ. NO. 395-612
DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST
AMP-J
REV. 10/93



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
→ ニッケル下地の土半田めっき
→ ニッケル下地の土にスズめっき

△	△	178306-5
△	△	178306-3
△	△	178306-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE

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tyco Tyco Electronics AMP K.K.
Electronics Kawasaki, Japan

12 POS DOUBLE ROW
HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100

WIRE RANGE	INSULATION DIA	NAME
mm (AWG)	mm	
MATERIAL	FINISH	(GENERAL TOLERANCE)
SEE NOTE	SEE NOTE	10MP ±0.3
注記参照	注記参照	10MS ±0.4
DR. 23 JUN 95	DE. 23 JUN 95	10MB ±0.45
CHK. Y. ISHIKAWA	APP. S. MANABE	10MC ±0.5
		10MD ±0.5

SIZE	LOC	NUMBER
A3	J	178306
SCALE	REV.	SHEET
2-1	B	1 OF 1

(CUSTOMER DRAWING) 顧客用図面